

IN THE CLAIMS

Please cancel Claims 13-20.

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Please add the following Claims 21-28.

Sub A

21. A method for securing a printed circuit board to a rigidizer comprising steps of:
applying a liquid adhesive to a top surface of the rigidizer;
curing the liquid adhesive during a first curing stage, after application of the liquid adhesive,
to produce a partially cured liquid adhesive;
placing the printed circuit board on the partially cured liquid adhesive; and
curing the partially cured liquid adhesive during a second curing stage to produce a fully
cured liquid adhesive.

22. The method of claim 21, wherein the step of applying the liquid adhesive to the top surface of
the rigidizer comprises a step of screening the liquid adhesive onto the top surface of the rigidizer.

23. The method of claim 21, wherein the liquid adhesive is a dual-cure system adhesive.

24. The method of claim 21, wherein the step of curing of the liquid adhesive during a first stage
produces a tacky adhesive that spreads, at most, a negligible amount when the printed circuit board is
placed on the partially-cured liquid adhesive.

25. The method of claim 21, further comprising a step of bending the printed circuit board and
the rigidizer after the second cure of the liquid adhesive.

26. The method of claim 21, wherein the liquid adhesive is a heat-curable liquid adhesive,
wherein the first cure comprises applying a first heating stage to the liquid adhesive and wherein the
second cure comprises applying a second heating stage to the liquid adhesive.

27. The method of claim 21, wherein the liquid adhesive can be cured by exposure to ultraviolet
radiation

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28. The method of claim 21, wherein the liquid adhesive can be cured by any one of a plurality of curing methods, wherein the first cure comprises applying a first curing method of the plurality of curing methods to the liquid adhesive and wherein the second cure comprises applying a second, different curing method of the plurality of curing methods to the liquid adhesive.

Attached hereto as ATTACHMENT A is a mark-up version of the changes made to the specification and claims by the current amendment and response. The attached pages are captioned "**Version with Markings to Show Changes Made.**"

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